Title (en)

METHOD OF CUTTING A MATERIAL BY A LASER MACHINE

Publication

EP 0403697 B1 19930127 (EN)

Application

EP 89124066 A 19891228

Priority

JP 15894189 A 19890620

Abstract (en)

[origin: EP0403697A1] A method of cutting a material comprises cutting a material by laser beams (3) emitted from a laser machine (1), and cleaning a cut surface of the material by water (11) as a solvent.

IPC 1-7

B23K 26/16

IPC 8 full level

B23K 26/14 (2014.01); **B23K 26/16** (2006.01); **B23K 26/38** (2014.01); **B23K 26/40** (2014.01)

CPC (source: EP US)

B23K 26/142 (2015.10 - EP US); **B23K 26/146** (2015.10 - EP US); **B23K 26/1462** (2015.10 - EP US); **B23K 26/16** (2013.01 - EP US)

Citation (examination)

- PATENT ABSTRACTS OF JAPAN vol.11, no. 155 (M-589), 20 may 1987 ; & JP - A - 61286087 (MITSUBISHIMELECTRIC CORP.)
- PATENT ABSTRACTS OF JAPAN vol. 7, no. 271 (M-260), 3 December 1983 ; & JP - A - 58151981 (TOKYO SHIBAURA DENKI K.K)

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 0403697 A1 19901227; **EP 0403697 B1 19930127**; DE 68904650 D1 19930311; DE 68904650 T2 19930603; JP H0323094 A 19910131; JP H06102277 B2 19941214; PT 92929 A 19910930; PT 92929 B 19971231; US 5043556 A 19910827

DOCDB simple family (application)

EP 89124066 A 19891228; DE 68904650 T 19891228; JP 15894189 A 19890620; PT 9292990 A 19900123; US 46257090 A 19900108